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Semiconductor Technology for Ultra Large
Scale Integrated Circuits and Thin Film
Transistors (ULSIC VS TFT 8)

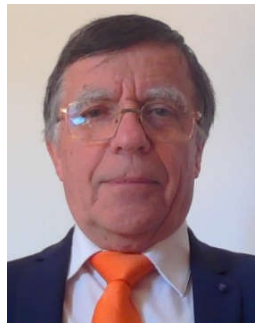
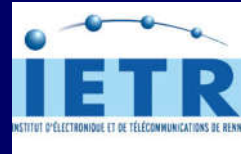
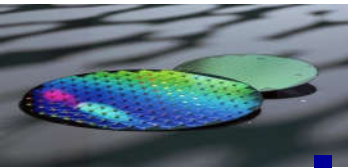
Proceedings

3-14-2023

**Invited; ULSI and TFT technologies joint forces to meet the future
challenges of a pervasive digital society**

Olivier Bonnaud

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ULSIC vs. TFT 8

May 15–18, 2023, Sapporo, Japan

Engineering Conferences International (ECI)

Semiconductor Technology for Ultra Large Scale Integrated Circuits and Thin Film Transistors 8

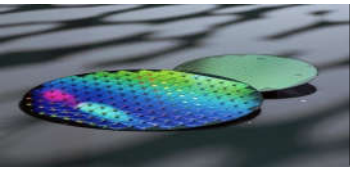
ULSI AND TFT TECHNOLOGIES JOINT FORCES TO MEET THE FUTURE CHALLENGES OF A PERVASIVE DIGITAL SOCIETY

Otaru (Japan), May 15-18, 2023

Olivier Bonnaud

Executive Director of GIP-CNFM (France)
Professor Emerite Univ. of Rennes - France





Introduction

The worldwide development of communication and data exchange systems has strongly encouraged the development of **digital technology**, growing exponentially since 2005.

The transparency of the operation of these tools does not highlight their **energy consumption!**

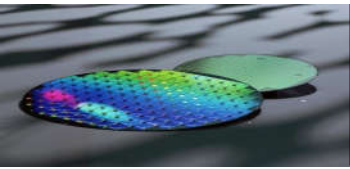
These **digital hardware** are physically made of **electronics** and **microelectronics**, highly integrated or of large area.

The solution is to **reduce the power consumption** of all electronics.

After presenting the context and the issues, my talk details the different proposals to **improve electronics**, by combining **both technologies**.

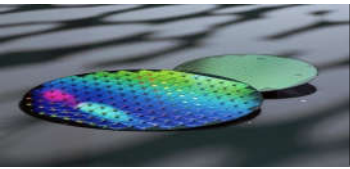
Furthermore, to face the challenges of electronics, **human resources** with **skills and know-how** covering a wide spectrum will be needed.

The corresponding strategy will close the presentation.



Outline

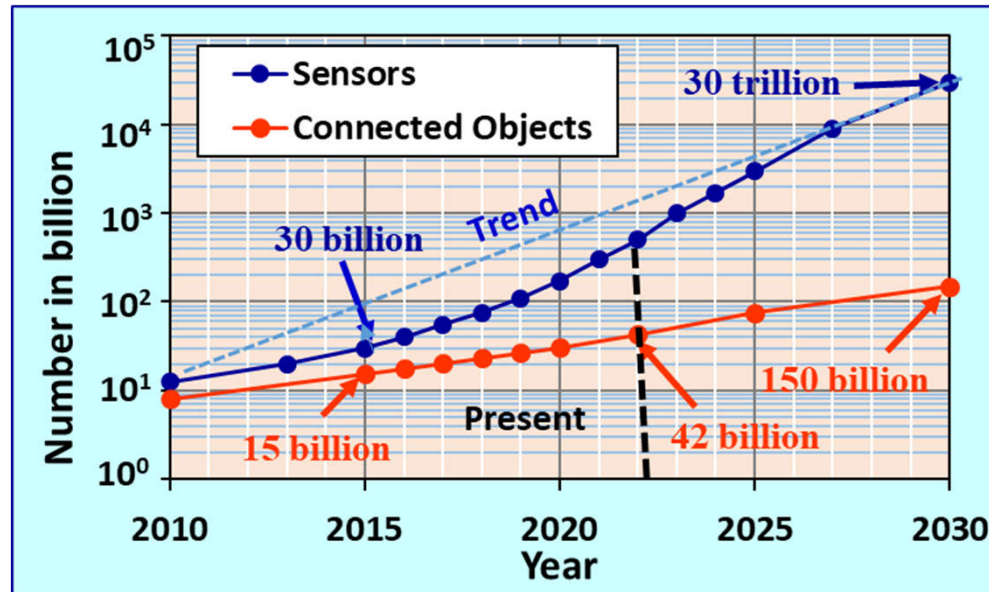
- Introduction
- **Huge evolution of digital society**
- Consequence on energy consumption and sustainable resources
- Challenges for electronics and microelectronics: ULSI & TFT roles
- Skills and jobs in shortage
- Strategy of the Microelectronics training
- Conclusion



Huge evolution of digital society

Exponential growing of Sensors & connected objects

The new **connected objects** include dozens of **sensors** (iPhone, iPad, PC). The global number of sensors is increasing exponentially like the number of connected objects.

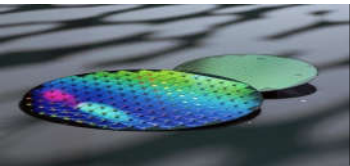


After O. Bonnaud, IJPEST, 10 (2), p. 115 (2016)

After J. Bryzek, iNEMI Spring Webinar, Berkeley, CA (2013)

After <https://www.postscapes.com/trackers/video/the-internet-of-things-and-sensors-and-actuators/>.





Huge evolution of digital society

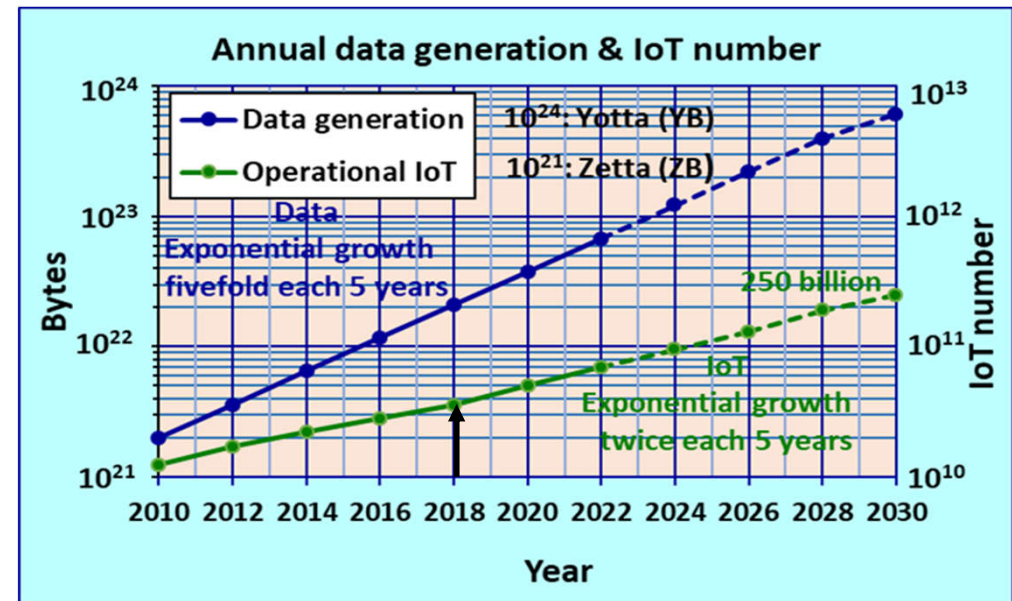
Exponential growing of data transfer and IoT

The amount of data transferred is X 10 each 4 years.
90% of the data is stored/processed by data centers.

- 10^{27} : Bronto (BB)
- 10^{24} : Yotta (YB)
- 10^{21} : Zetta (ZB)
- 10^{18} : Exa (EB)
- 10^{15} : Peta (PB)
- 10^{12} : Tera (TB)

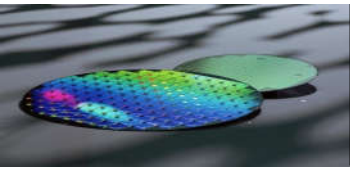
The number of IoT is x2 each 5 years and will reach 250 billion in 2030.

Since 2018, the growth is faster due to cryptocurrencies (Bitcoin, Litecoin, or Ethereum), the 5G, and artificial intelligence



After J. Desjardin, World Economic Forum, 17 April 2019

After O. Bonnaud, IJPEST, vol. 14, n° 1, pp. 1-8, , 2020



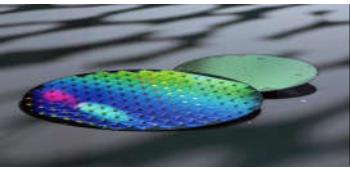
Huge evolution of digital society

Huge involvement of electronics devices circuit and systems

The hardware associated to digital world, such as connected objects and IoT is mainly based on **electronics and microelectronics components and devices**:

- Integrated circuits (microprocessors, DSP, memories, digital/analog converters, ..),
- Embedded electronics (FPGA, Arduino,..),
- Large area devices and systems (flat panel displays, sensors, actuators, energy harvesters, ..),
- High frequency systems (antennas, amplifiers, modulators,..),
- Hybrid packaging (3D stacking,..),
- Power electronics devices and circuits (power supply, voltage converters, ..).

All these devices are **electrical power consuming** even in off-state.



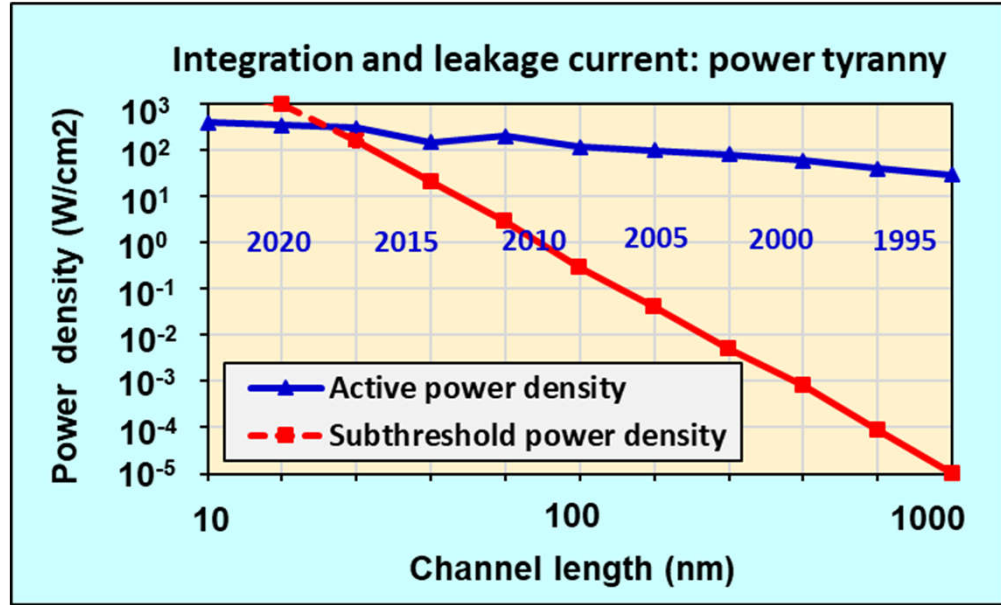
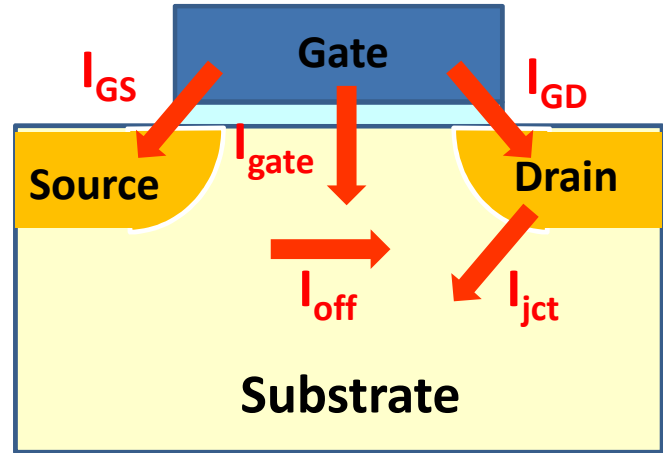
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Consequence on energy consumption and sustainable resources

Origin of the power electrical consumption (1/3)

Smaller the device, higher the relative leakage currents!

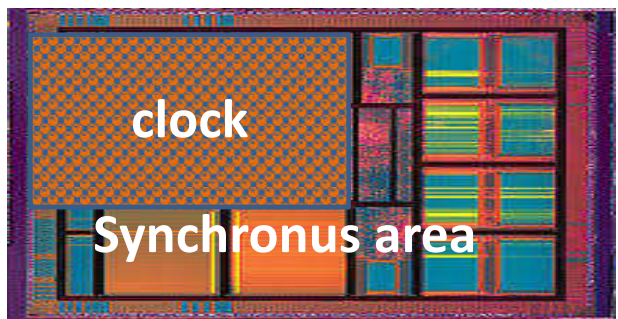


After W. Haensch, *IBM J. Res. Dev.* 339 (2006)

After O. Bonnaud et al, *PETI*, 9, p. 01 (2018).

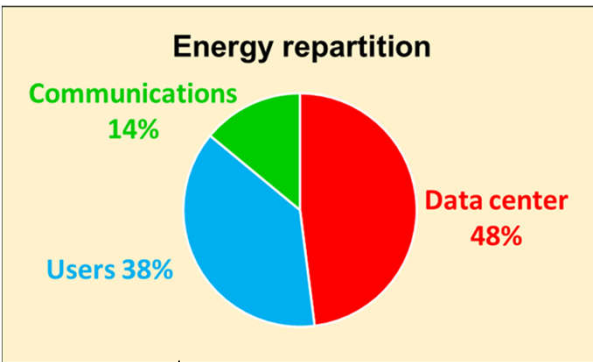


In synchronous technologies: billions of transistors are driven simultaneously by the clock that occupies up to 1/3 of the area.



Consequence on energy consumption and sustainable resources

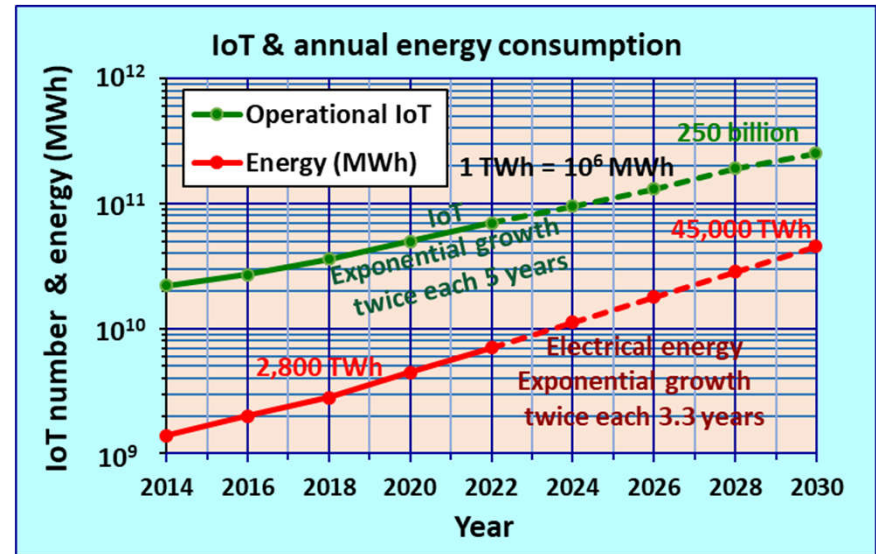
Origin of the power electrical consumption (2/3)



In 2018, each 1GB data transferred induced an electrical energy consumption of 2 kWh at least taking into account of all the digital chain

Transoceanic optical fiber cable

- optical loss 0.5dB/km, - length 6,000 to 10,000 km,
- an amplifier/repeater every 80 km (gain 10^4)!
- 7 cm conductor diameter for 4 fibers (15kV, 40MW).



After <https://www.src.org/about/decadal-plan/>

IoT consumption growth: x2 each 3.3 years since 2005
Global IoT consumption in 2030 : 45,000 TWh

Origin of the power electrical consumption (3/3)

6.000 TWh lost for transport/conversion, 26% of the consumption: power electronics is seriously concerned



Consequence on energy consumption and sustainable resources

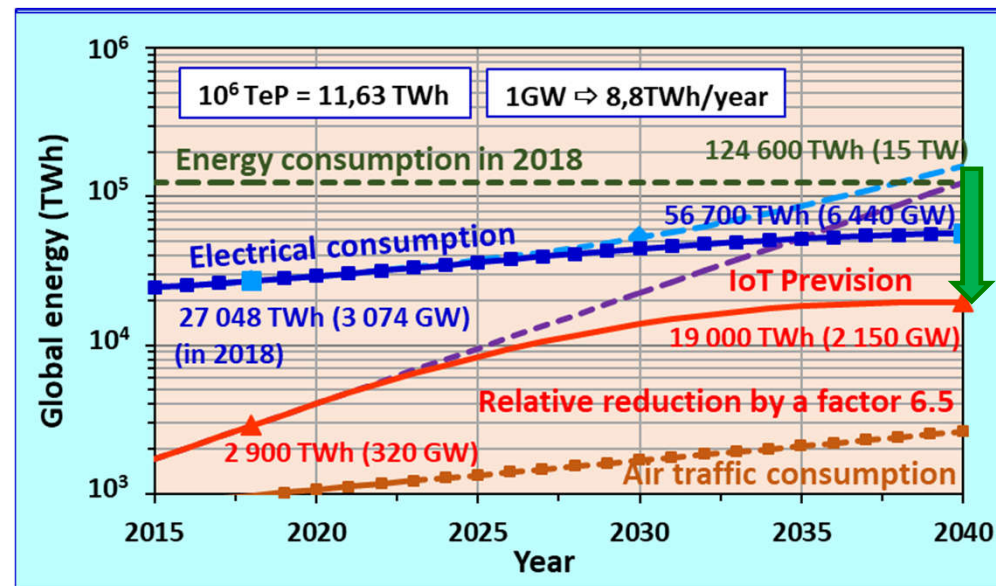
Reduction of the exponential growing of electrical energy consumption

The IoT energy consumption is exponential and will reach non-realistic level in 2040.

To avoid a dead-end, the solution is the **electronics improvement.**

It is possible to progressively **decrease by a factor 10** the total consumption of electronics with innovation over the next fifteen ears .

Global elect. Consump. in 2018 : **30,000 TWh**
IoT Consump in 2030 **higher without action**
IoT Consump. in 2040 **less than 20,000 TWh!**



This evolution is simulated!

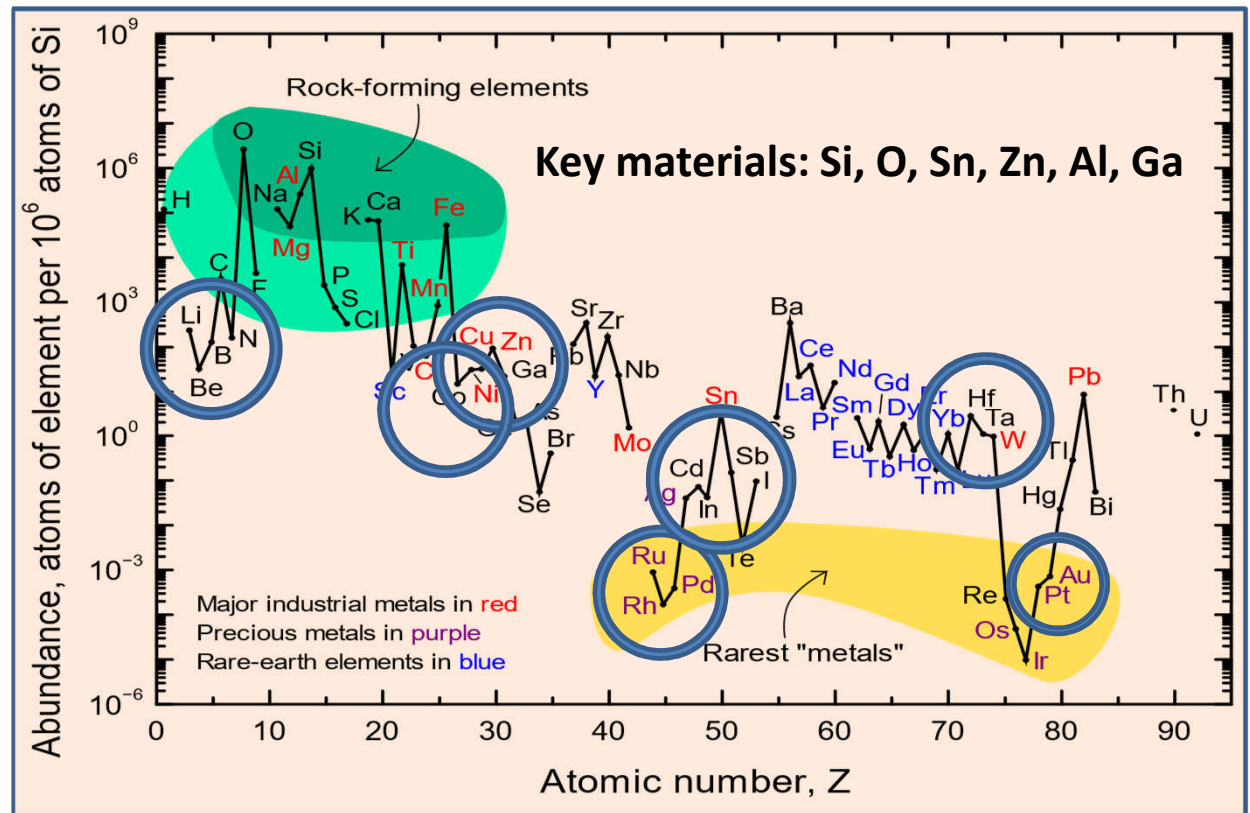
After O. Bonnaud, Int. J. Plasma Environ. Sci. Technol. vol. 14, n° 1, pp. 1-8, , 2020

After J-R. Léquepeys et al., Proc. ESSCIRC 2021, p. 7-14

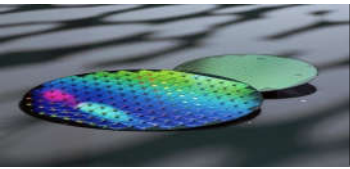
Consequence on energy consumption and sustainable resources

Sustainable resources: abundance of elements in the earth crust

- The **lower the abundance**, the higher the complexity of the extraction and purification, the **higher the energy consumption**.
- For the less abundant elements, the available natural sources are mostly concentrated in a few regions of the planet.
- For electronic applications Ga, In, As, Hf, Sb, and Li, Co (battery's) are concerned.

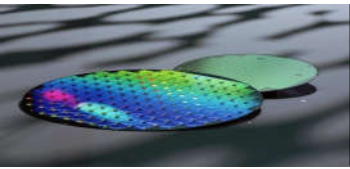


After CRC Handbook of Chemistry and Physics, 97th edition (2016–2017)



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Challenges for electronics and microelectronics: ULSI & TFT roles

Challenges in micro-nanoelectronics

Process

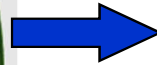
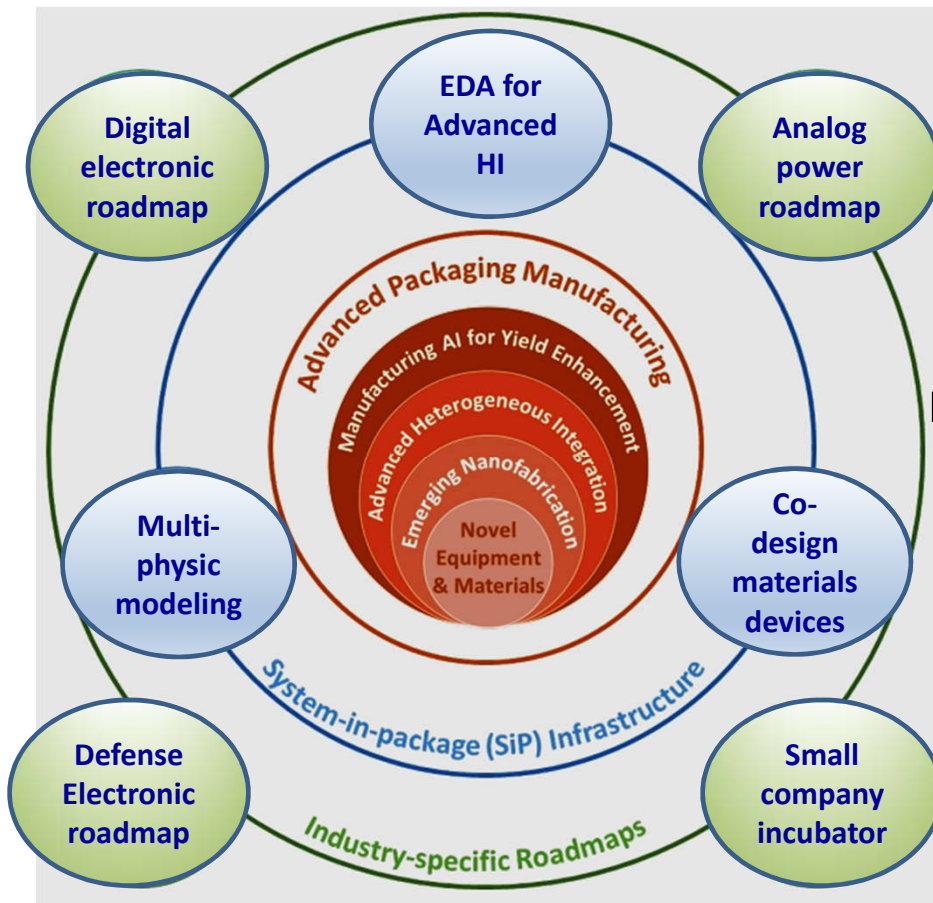
- Creating active and passive **new nanometric components** with infinitesimal electrical consumption and with **new materials (wide bandgap and 2D materials)**,
- Increasing the electronic **operating frequencies** in order to increase data flow,
- Improving the **efficiency of power electronics**: components and circuits
- Developing **energy harvesting systems, integration** in 3D architectures.

Design

- Adapting **circuit architectures** that can monitor the idle of areas,
- Combining **asynchronous** and **synchronous** electrical IP,
- Developing systems for "**edge-computing**" which enable **locally** treatment ,
- Opening up the spectrum of electronics applications by **3D** integration,
- Focusing the electronic innovation on **sustainability**.

Challenges for electronics and microelectronics: ULSI & TFT roles

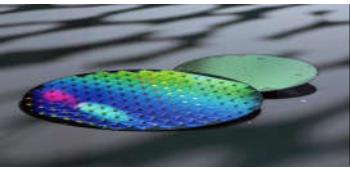
Texas Institute for Electronics Program Overview (US Chips Act): towards applications



Application Areas
Cloud Computing and AI
Electric Vehicles and Automotive Systems
Consumer/Mobile Electronics and Edge Computing
Healthcare and Wearable Electronics
High Power Electronics
Communications
Aerospace Applications
Sensors, Actuators and Micro Electro-mechanical Systems
Quantum Computing

After V. Sreenivasan, Un. TA, Nov.2022





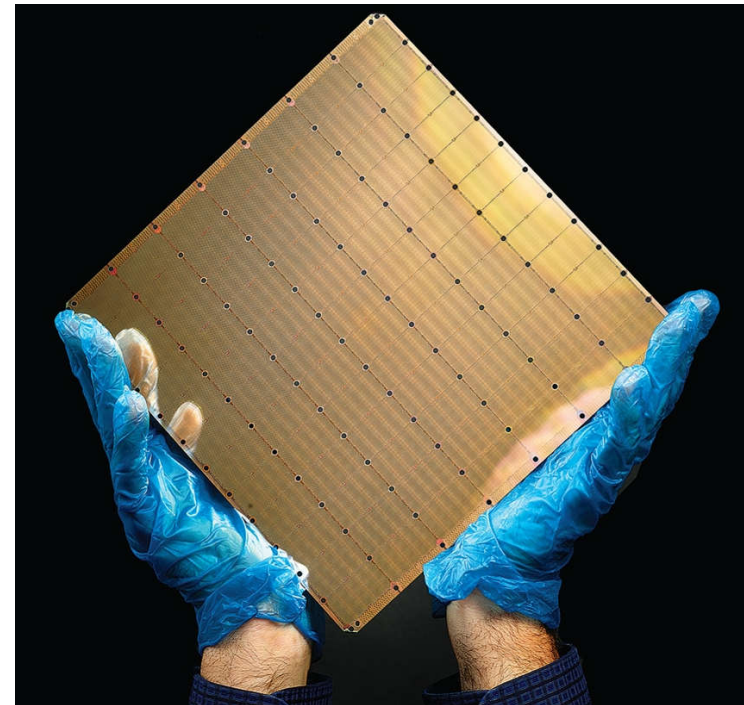
Challenges for electronics and microelectronics: ULSI & TFT roles

New ULSI Integrated circuit for AI application: challenge on the large area

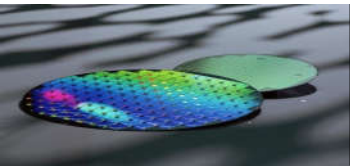
Integrated circuit, 7nm technology, 2.6 trillion transistors, 850,000 cores, 220 Pbytes/s, 4.6 dm²

Larger area with good production yield allows much more complex circuits and systems.

The large area allows power dissipation in this case!



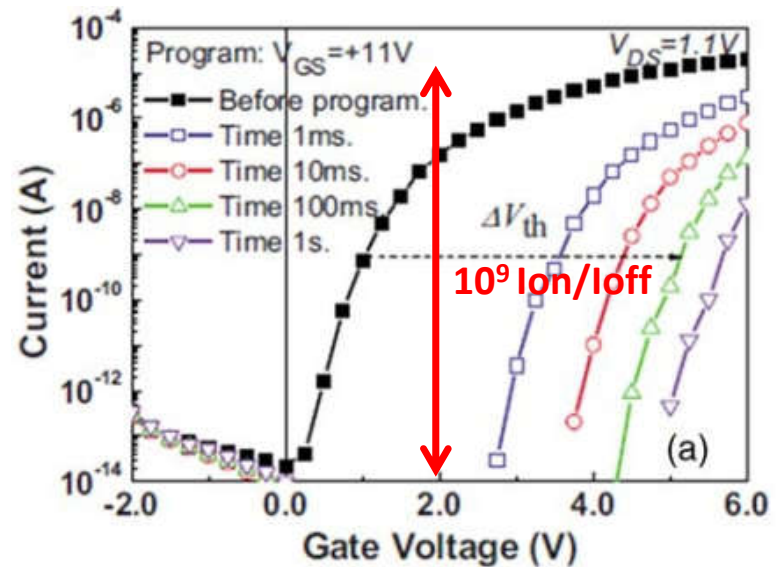
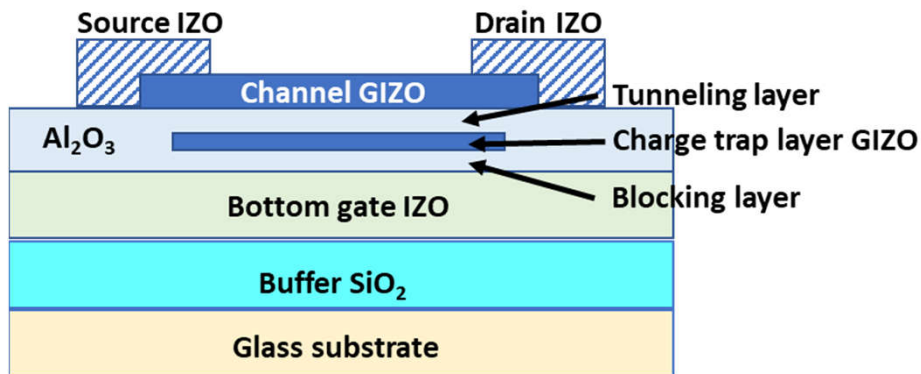
After S.M. Moore, Cerebras's silicon-wafer-size chip boasts 2.6 trillion transistors, IEEE spectrum, July 2021



Challenges for electronics and microelectronics: ULSI & TFT roles

New devices based on metal-oxide-semiconductor: role of TFT

The main interest is to have a very high I_{on}/I_{off} ratio in this elementary memory ($\approx 10^9$).
Charges are trapped in GIZO (GaInZnO)



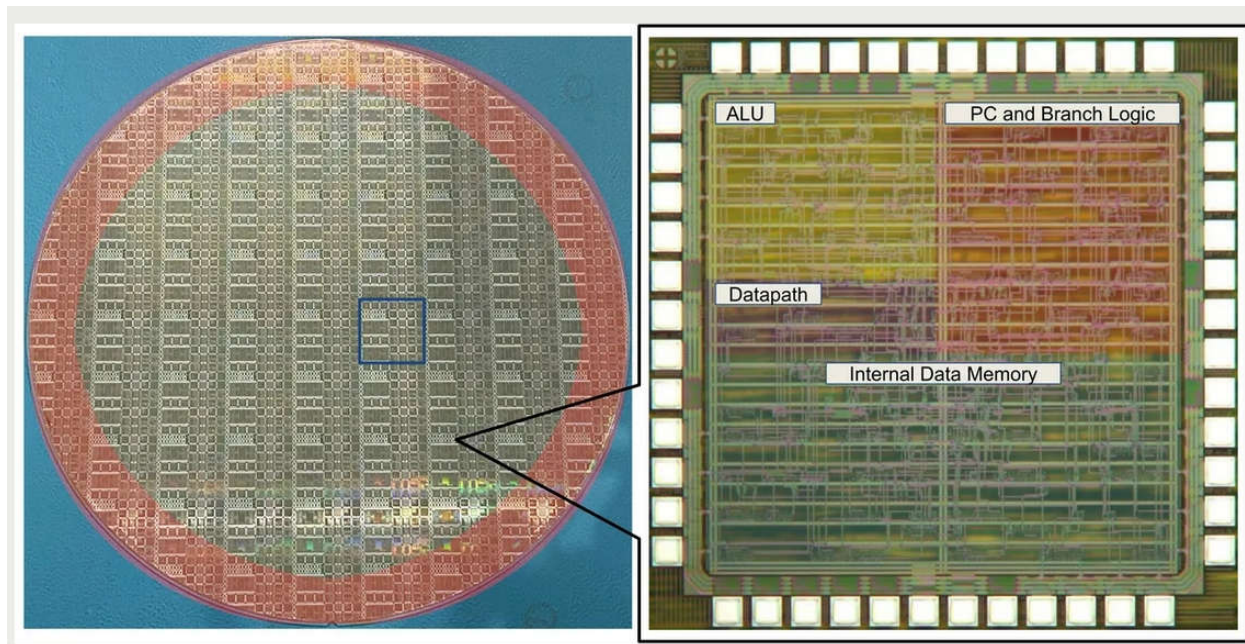
After M. Kimura, Jpn. J. Appl. Phys. 2019 , 58, pp:1-10



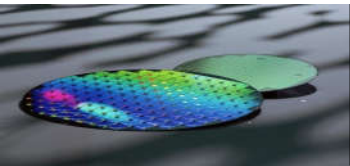
Challenges for electronics and microelectronics: ULSI & TFT roles

New TFT-based integrated circuit for low-power applications: IGZO-based

4-bit microcontroller on plastic, the first yield study on plastic processors (4004 Intel based architecture).
Flexible thin-film semiconductor indium gallium zinc oxide (IGZO), which can be built on plastic.
 I_{on}/I_{off} ratio is much higher than usual Silicon IC devices?



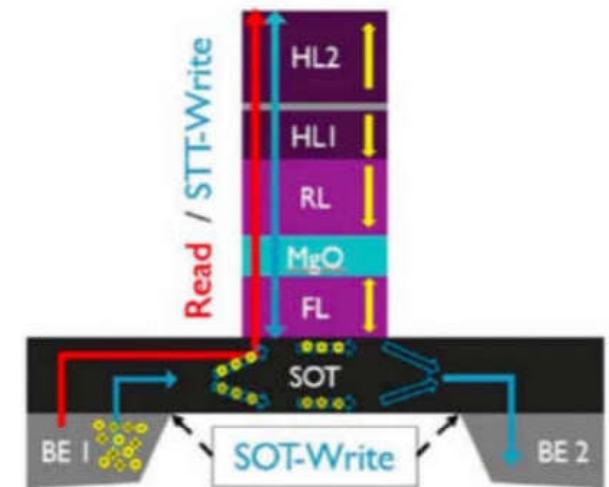
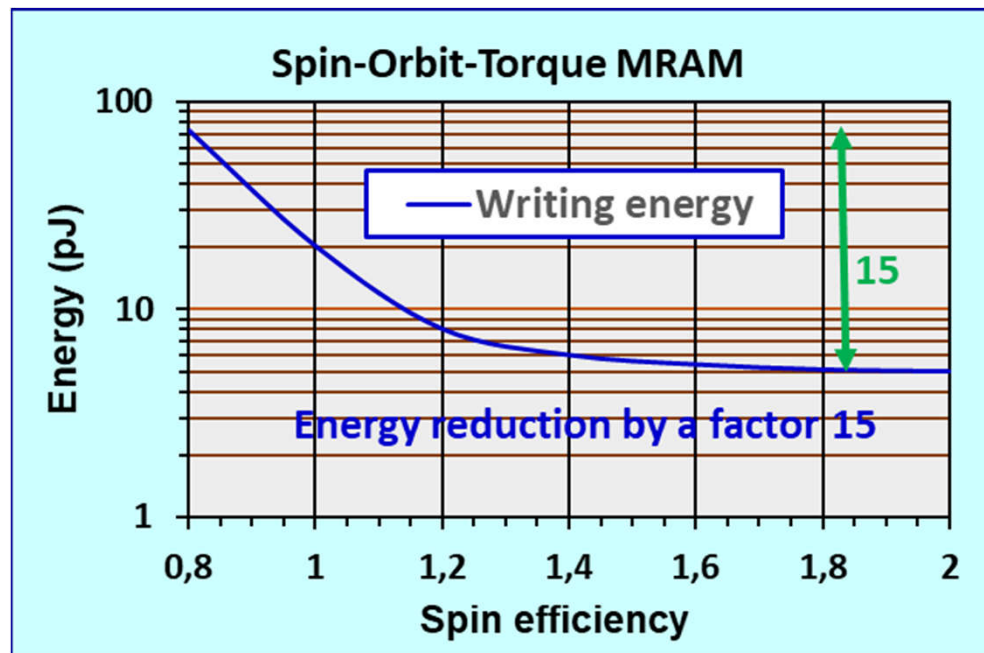
After S.K. Moore, The First High-Yield, Sub-Penny Plastic Processor”, IEEE Spectrum Journal, August 2022



Challenges for electronics and microelectronics: ULSI & TFT roles

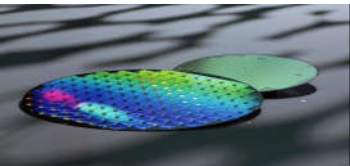
New low-energy consumption memory: SOT-MRAM (3D mixed device)

Combining ULSI & TFT allows a main writing energy 15 times lower ($\approx 5 \times 10^{-12}\text{J}$).



After M. Gupta et al., Proc. IEDM 2020, pp. 24.5.1-24.5.4, 2020

After M. Gupta et al., Proc. ESSDERC 2022, pp.241-244, 2022



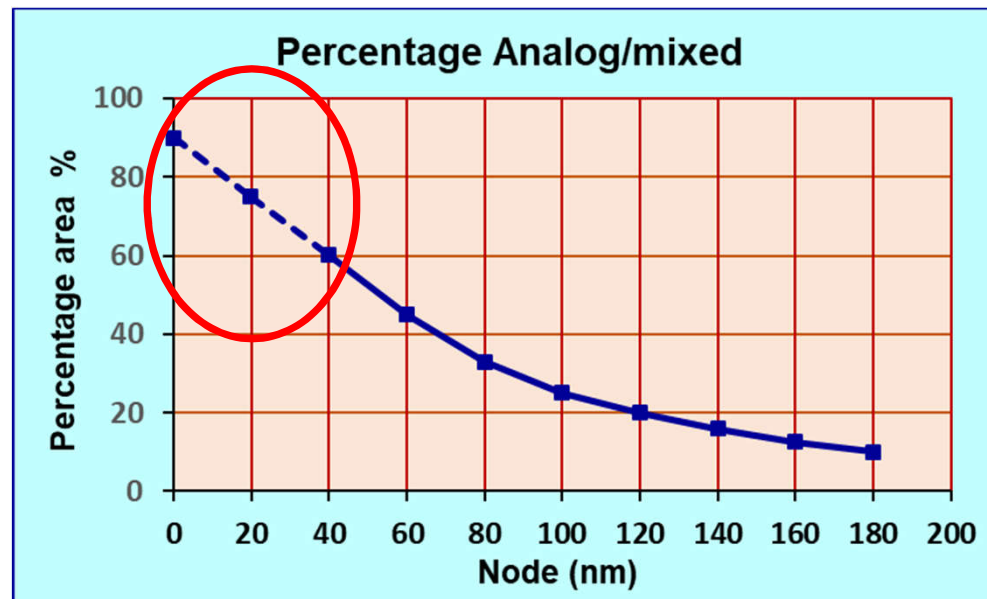
Challenges for electronics and microelectronics: ULSI & TFT roles

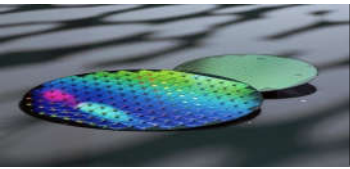
Relative increase of analog electronic involvement

The percentage of **analog functions** in the new integrated circuits allows a decrease of the power consumption of the application at off-state.

This approach is very important for the digital data treatment.

This means a growing need for specialist in **analog electronics both ULSI and TFT based**.





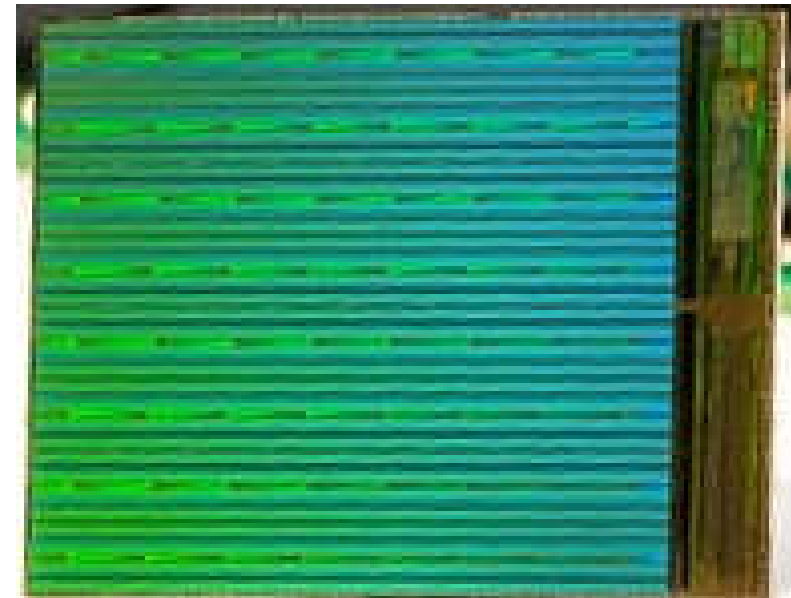
Challenges for electronics and microelectronics: ULSI & TFT roles

Higher integration thanks to 3D approach: role of packaging

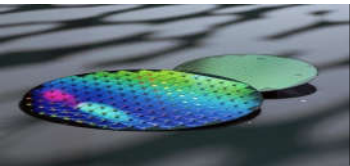
Stacking of 48 dies for a new prototype of Flash memory: 10 Tbytes.

The integrated packaging allows very high complexity systems.

This approach imposes a very **low power dissipation** of each die! The challenge lies in the elementary devices and the architecture of integrated functions



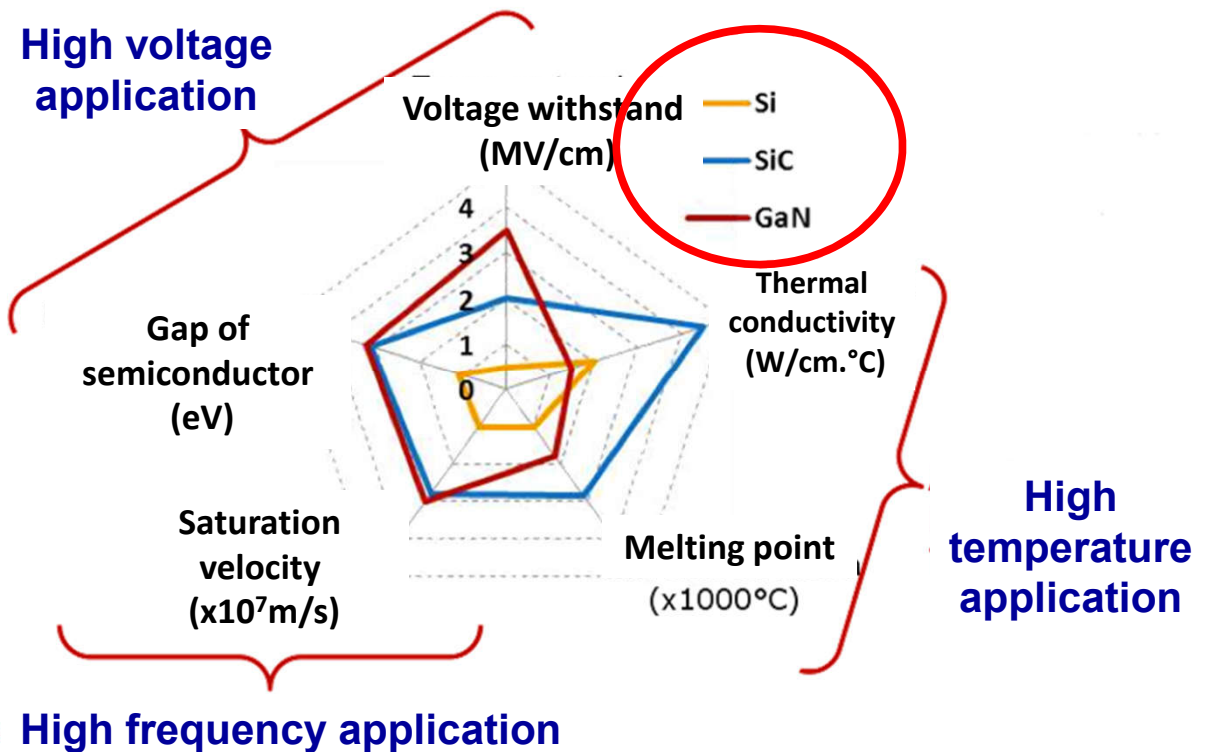
From Intel, Nand Flash 10Tb, 2015

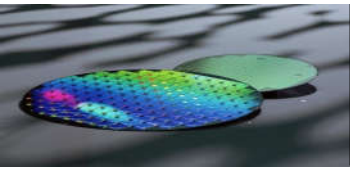


Challenges for electronics and microelectronics: ULSI & TFT roles

Introduction of new materials for power devices: Si, SiC, GaN

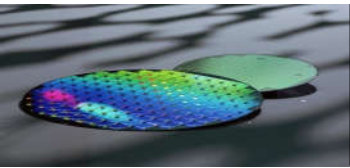
Depending on the application domain of power electronics, the semiconductor materials have specific properties. SiC and GaN allow a decrease of leakage current at **high voltage** or **high frequency**.





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Skills and jobs in shortage

All these improvements will only be achieved if the **human potential** capable of bringing innovation is developed.

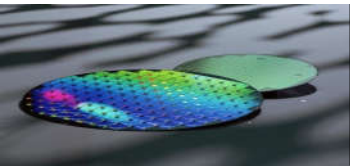
At the global level, the profession is observing a growing **deficit of skills** corresponding to **jobs in high shortage**.

It is urgent to increase the **pool of specialists** in the field and adapt the pedagogical approach that can be focused on **knowledge and know-how**.

If a part of the knowledge can be acquired from digital tools on line (MOOC), the know-how must be acquired on physical equipment and platforms with face-to-face training.

In the following we will analyze:

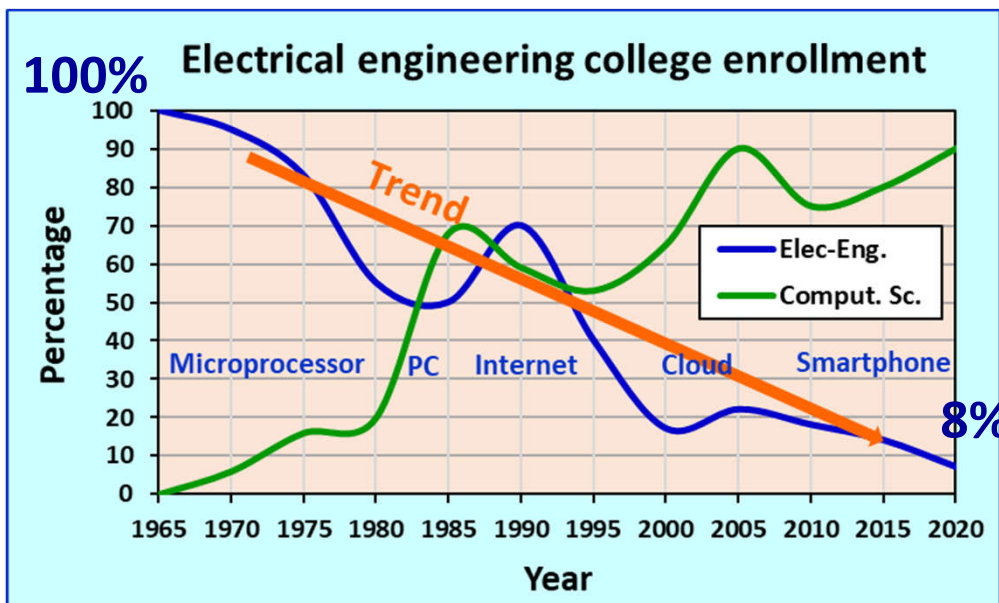
- Human **resource limitations**
- **Disaffection of sciences** and Electrical Engineering
- Jobs in **shortage**
- Teacher shortage in Higher education



Skills and jobs in shortage

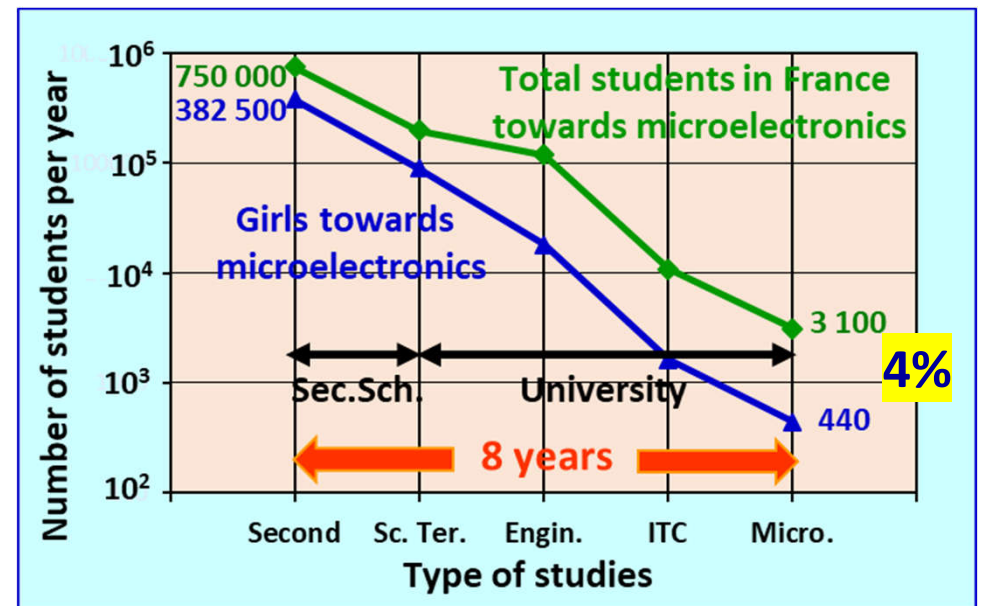
Human resource limitations

No longer attractive for young people. A large part of the Electrical engineering pool was transferred to Computer sciences one (USA example).



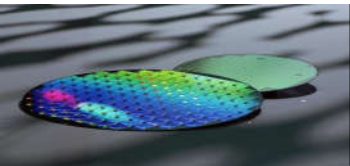
After R. Koduri, IEEE VLSI Symp., 2022 (Intel Vice-President)

Less and less students in the EE field in France. Only 4% of students population are graduate. Among them, only 14% of females.



After O. Bonnaud, IMAPS'22, 2022

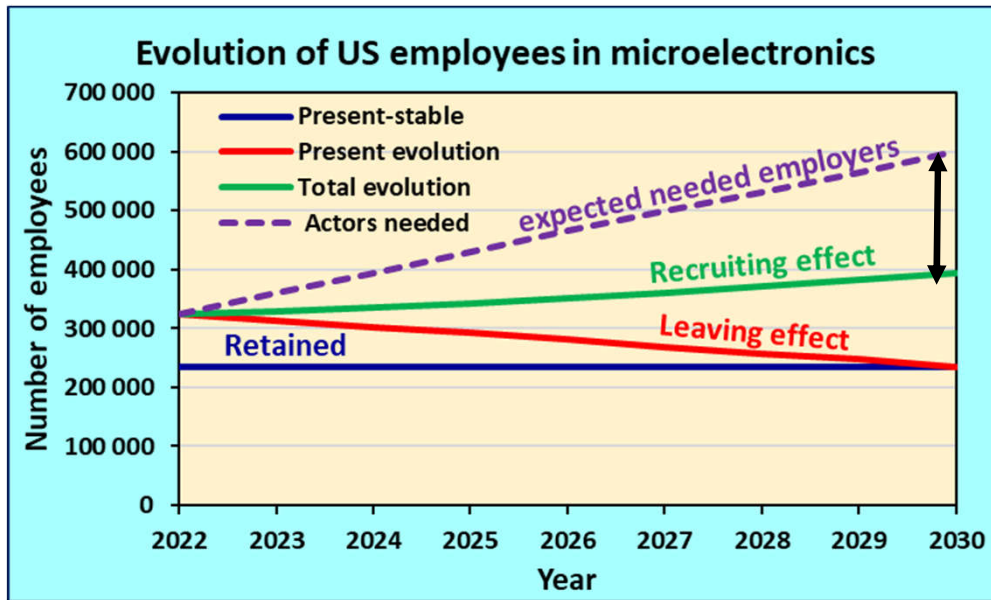




Skills and jobs in shortage

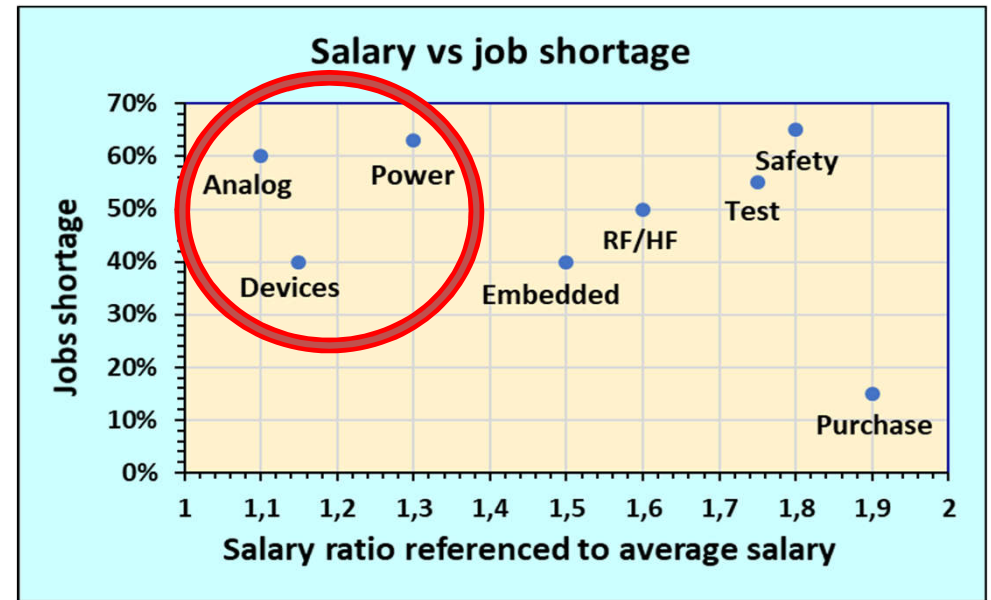
Disaffection of sciences and Electrical Engineering

Disaffection with science and electrical engineering. Forecasting the changing U.S. workforce.



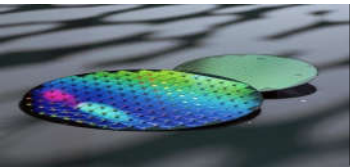
From Intel, Nand Flash 10Tb, 2015

Effect of salary on jobs shortage. People working in marketing are favored! Technique is less considered!



From Konexio analysis, 2022





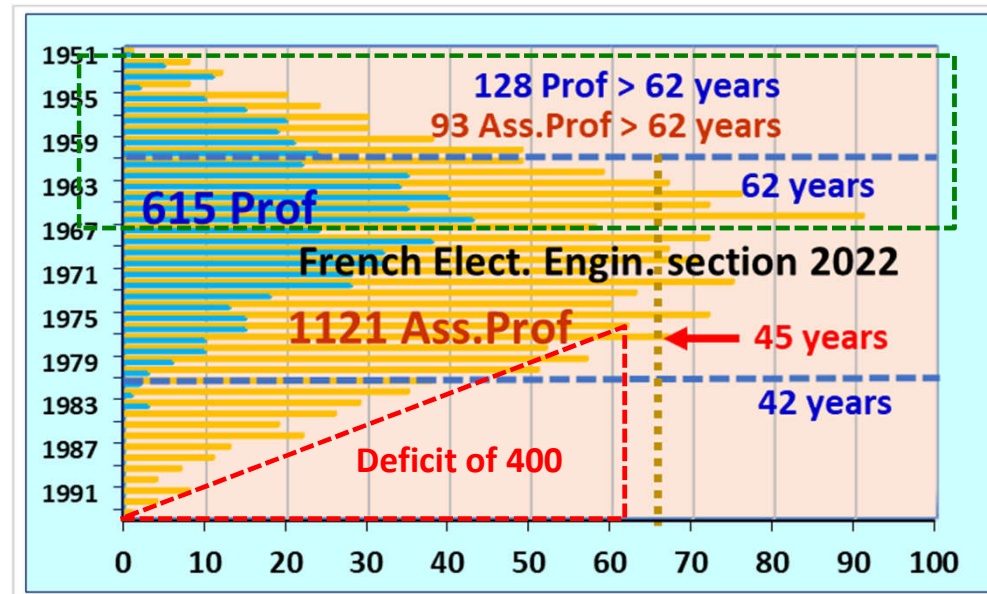
Skills and jobs in shortage

Teacher shortage in French Higher education

Academic teachers in shortage in electrical engineering: the age pyramid shows a strong recruitment deficit for teachers under 45 years old more than 400 in 2022.

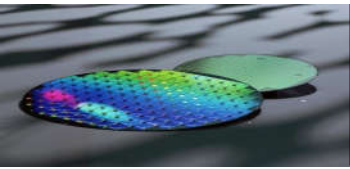
Since 2007, the number of teachers in the field has continuously decreased.

In addition, more than 500 teachers will be retired by 2027!



After O. Bonnaud, Report of CNU'63, France , 2022





Skills and jobs in shortage

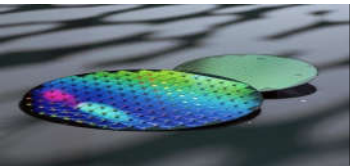
Human resource: jobs in shortage declared by French industry

Process

- In the field of technological process:
 - electronic and clean room **operators** (microelectronic processes),
 - production machine **technicians/engineers**,
 - **process engineers** in microelectronics,
 - technicians/engineers for the **manufacturing of electronic boards** (printed circuits).

Design

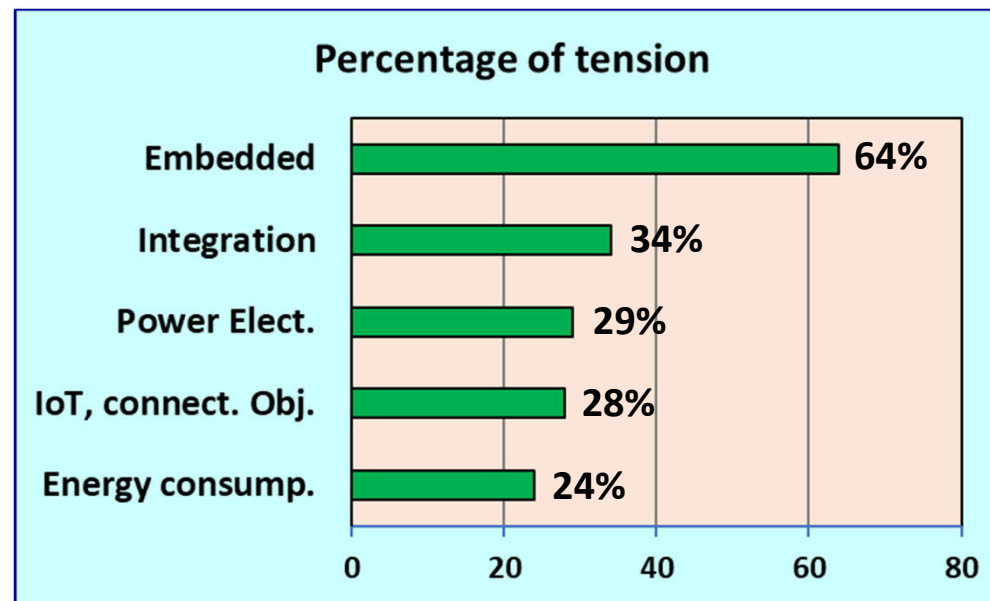
- In the field of design:
 - **analog design** engineers,
 - **test product** engineers,
 - **development** engineers,
 - **architectural** engineers,
 - design engineers of **electronic boards**.



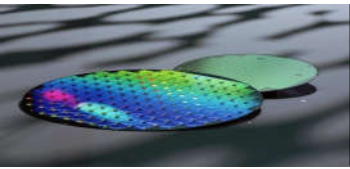
Skills and jobs in shortage

Jobs in shortage and tension on recruitment

The needs identified by CSF in terms of skills are split according to the following themes: the **percentage indicated** corresponds to the **degree of tension on recruitment position not satisfied**.

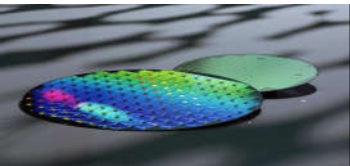


After Report of CSF France , 2022



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- Conclusion



Strategy of the Microelectronics training

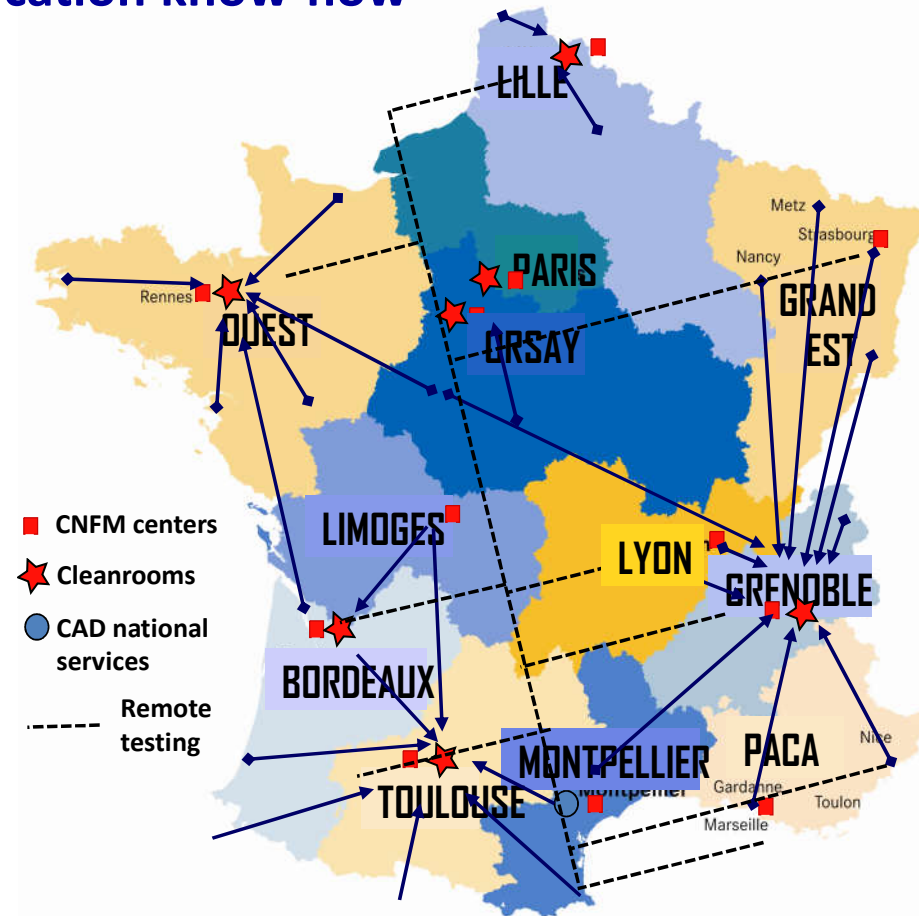
The French network for Higher Education know-how

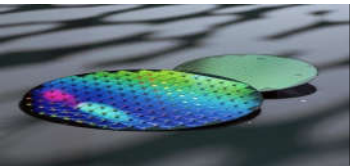
The structure of GIP-CNFM network is in the form of a **Public Interest Grouping or Consortium (GIP in French)** entitled **National Coordination for Training in Microelectronics and Nanotechnologies (CNFM in French)**.

The goal: to **share the functioning** of advanced platforms offering a wide spectrum of innovative **know-how training**.

12 academic structures & ACSIEL
12 CNFM centers - 7 clean-rooms
National CAD services for testing, software's, prototyping
18,000 students /year 150 training courses

After O. Bonnaud *et al.*, ECS Transactions, 64 (10), 187-192 (2014)





Strategy of the Microelectronics training

The French network for Higher Education know-how
Varieties of technologies in the Higher education training



Cleaning of IC wafers
in cleanroom



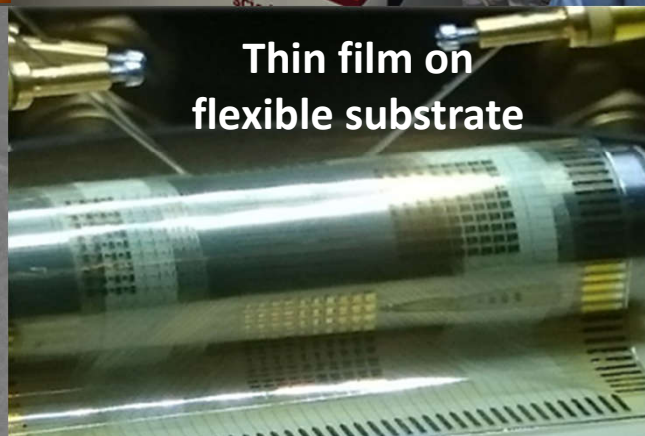
ALD for ULSI 3D
devices



Deposition process
in cleanroom



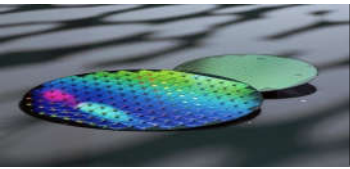
Thin film devices
for 3D architecture



Thin film on
flexible substrate



Thin films for
MEMS application



Strategy of the Microelectronics training

Attractivity of young schoolers and employees

Each year, many classes are coming on platforms for a one day know-how experiment.

This experience makes them aware. Not enough schoolers are trained! The strategy: increase their number!



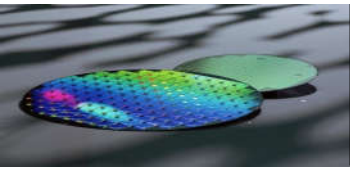
New digital tools involved in higher education

The ministry strategy encourages the developing of digital tools and distance learning in order to minimize the face-to-face between professors and students.

Several tools were developed by the network to prepare the students to the practical training.

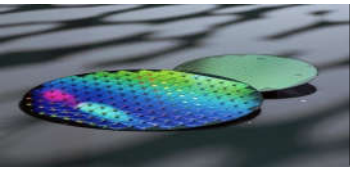
This pedagogical approach was experienced during the COVID-pandemic.





Outline

- **Introduction**
- **Huge evolution of digital society**
- **Consequence on energy consumption and sustainable resources**
- **Challenges for electronics and microelectronics: ULSI & TFT roles**
- **Skills and jobs in shortage**
- **Strategy of the Microelectronics training**
- **Conclusion**



Conclusion

The proper training of engineers and masters in microelectronics, requires the **acquisition of know-how**.

The key points of the current strategy to meet the challenges of microelectronics are :

- **adapting content** to the industrial needs,
- developing knowledge, know-how in **ULSI & TFT technologies**,
- preparing trainees for a more efficient **acquisition of know-how on platforms**,
- creating **new training platforms** targeting skills and know-how deficits,
- preparing the future engineers and doctors to **innovation** in order to **face the future challenges**,
- increasing the **awareness of young people** in secondary school to enlarge the pool of skills.

This field, which is at the center of societal evolution, requires rapid and appropriate adaptation, which is a **long-term objective** over several years, both in Europe and worldwide.

Acknowledgement

Special thank to my colleagues of the CNFM **national network** for their contribution in many works and to my executive assistant for her **technical support** in the preparation of this presentation.

ご清聴ありがとうございました
Thank you for your attention

